MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
 - $P_{1dB} = 37.5 \text{ dBm}$ at 10.7 GHz to 11.7 GHz
- High gain
- G_{1dB} = 7.0 dB at 10.7 GHz to 11.7 GHz
 Broadband internally matched
- Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P _{1dB}	V _{DS} = 9V f = 10.7 - 11.7 GHz	dBm	37.0	37.5	-
Power Gain at 1dB Compression Point	G _{1dB}		dB	6.0	7.0	-
Drain Current	I _{DS}		Α	-	2.0	2.5
Power Added Efficiency	η_{add}		%	-	20	-
Channel-Temperature Rise	ΔT_{ch}	V _{DS} x I _{DS} x R _{th (c-c)}	°C	-	-	80

Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	V _{DS} = 3V I _{DS} = 2.4A	mS	-	1400	-
Pinch-off Voltage	V _{GSoff}	V _{DS} = 3V I _{DS} = 72 mA	V	-2	-3.5	-5
Saturated Drain Current	I _{DSS}	V _{DS} = 3V V _{GS} = 0V	Α	-	5.0	5.7
Gate-Source Breakdown Voltage	V _{GSO}	I _{GS} = -72 μA	V	-5	-	-
Thermal Resistance	R _{th (c-c)}	Channel to Case	°C/W	-	3.0	3.7

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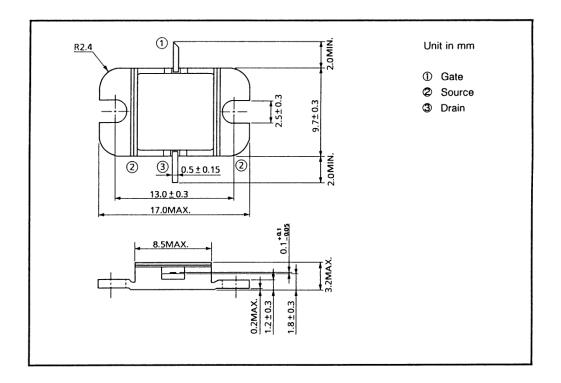
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The information contained here is subject to change without notice.

Absolute Maximum Ratings ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _D	Α	5.7
Total Power Dissipation (T _c = 25°C)	P _T	W	30
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65 ~ 175

Package Outline (2-9D1B)

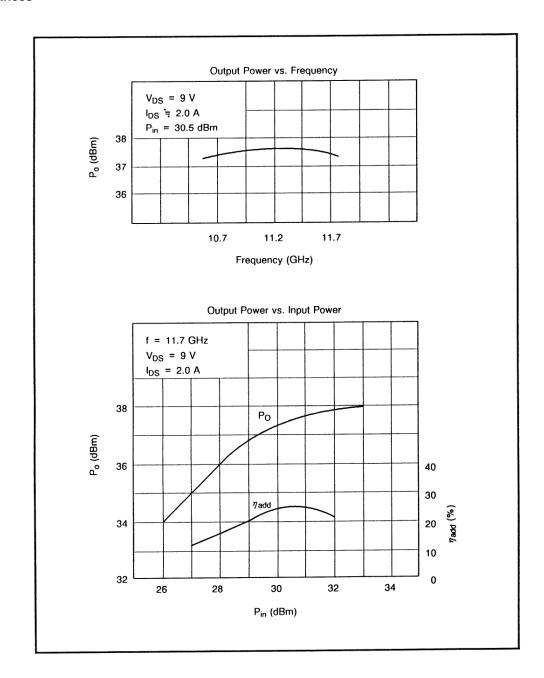


Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

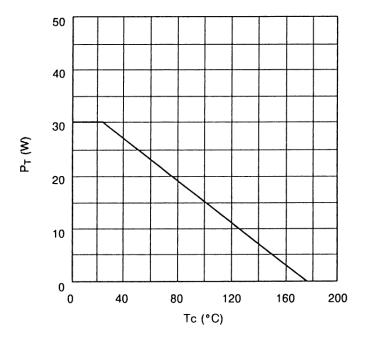
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RF Performances



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Power Dissipation vs. Case Temperature

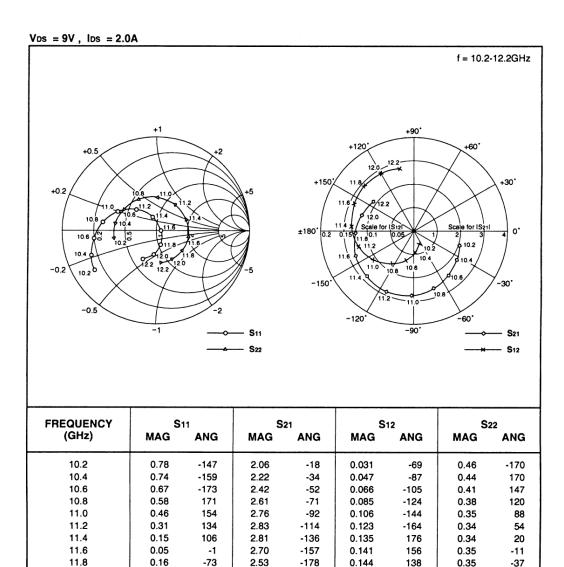


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TIM1011-5 S-Parameters (Magn. and Angles)

12.0

12.2



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-96

-115

2.33

2.14

163

144

0.141

0.136

120

103

0.35

0.35

-61

-82

0.26

0.34